Renesas Electronics America Inc - R5F2LA64ANFP#U0 Datasheet

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I²C, LINbus, SIO, SSU, UART/USART
Peripherals	LCD, POR, PWM, Voltage Detect, WDT
Number of I/O	56
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LFQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f2la64anfp-u0

Table 1.4 LCD Display Function Pins Provided for Each Group (R8C/LA3A Group, R8C/LA5A Group)

Shared I/O Port	R8C/LA3A Group Common output: Max. 4 Segment output: Max. 11								R8C/LA5A Group Common output: Max. 4 Segment output: Max. 27							
P0	—	—	—	—	—	—	—	—	SEG 7	SEG 6	SEG 5	SEG 4	SEG 3	SEG 2	SEG 1	SEG 0
P2	SEG 15	SEG 14	SEG 13	SEG 12	SEG 11	SEG 10	SEG 9	SEG 8	SEG 15	SEG 14	SEG 13	SEG 12	SEG 11	SEG 10	SEG 9	SEG 8
P3	—	—	—	—	—	—	—	—	SEG 23	SEG 22	SEG 21	SEG 20	SEG 19	SEG 18	SEG 17	SEG 16
P5	—	VL3 (2)	VL2 (2)	VL1 (2)	COM 0	COM 1 SEG 26	COM 2 SEG 25	COM 3 SEG 24	—	VL3 (2)	VL2 (2)	VL1 (2)	COM 0	COM 1 SEG 26	COM 2 SEG 25	COM 3 SEG 24

Notes:
1. The symbol "—" indicates there is no LCD display function. Set the corresponding bits to 0 by setting registers LSE0, LSE2, and LSE5 for these pins.
2. When using the LCD drive control circuit, set the corresponding bit in the LSE5 register to 1.

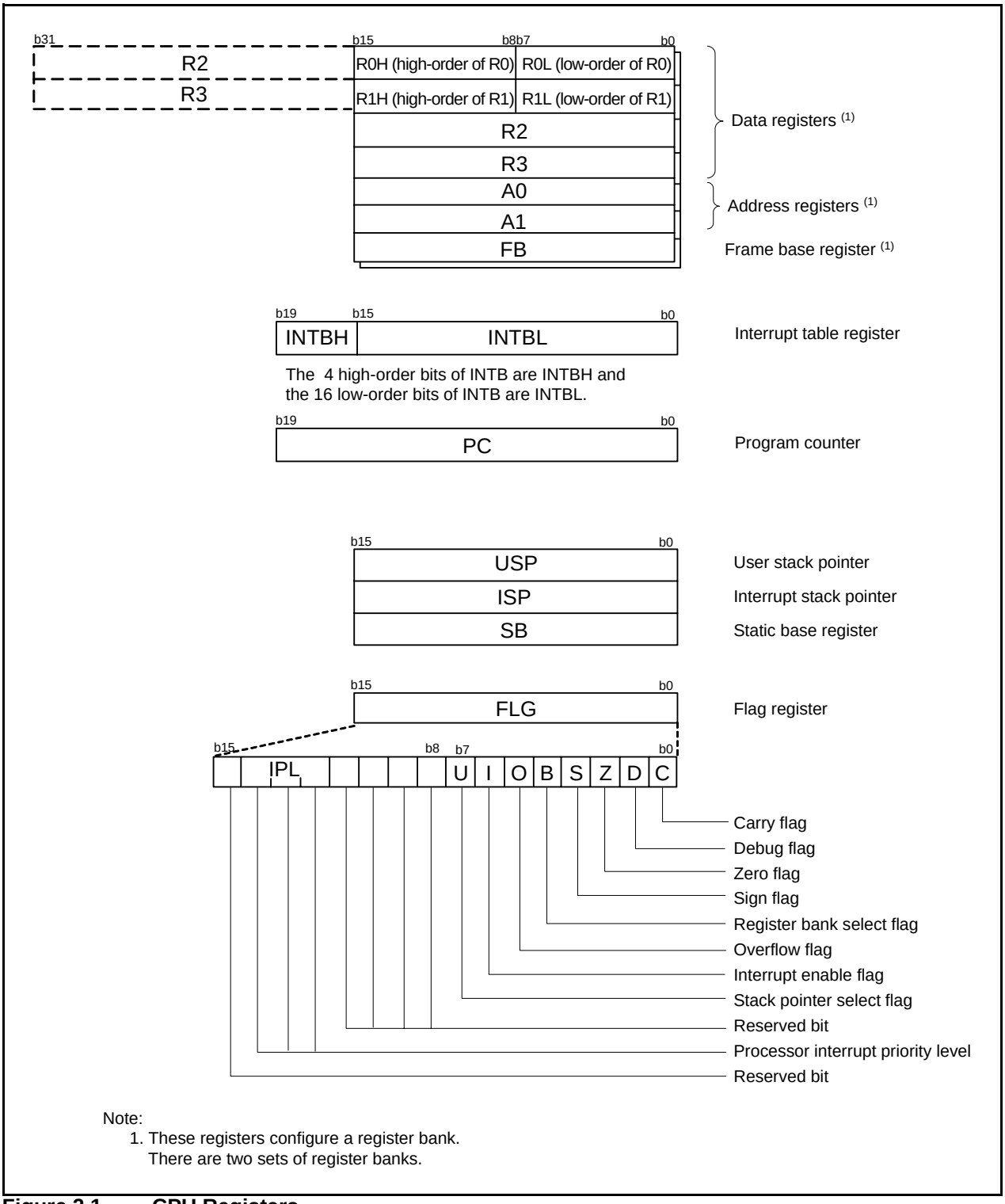
Table 1.5 LCD Display Function Pins Provided for Each Group (R8C/LA6A Group, R8C/LA8A Group)

Shared I/O Port	R8C/LA6A Group Common output: Max. 4 Segment output: Max. 32								R8C/LA8A Group Common output: Max. 4 Segment output: Max. 40							
P0	SEG 7	SEG 6	SEG 5	SEG 4	SEG 3	SEG 2	SEG 1	SEG 0	SEG 7	SEG 6	SEG 5	SEG 4	SEG 3	SEG 2	SEG 1	SEG 0
P1	SEG 15	SEG 14	SEG 13	SEG 12	SEG 11	SEG 10	—	—	SEG 15	SEG 14	SEG 13	SEG 12	SEG 11	SEG 10	SEG 9	SEG 8
P2	SEG 23	SEG 22	SEG 21	SEG 20	SEG 19	SEG 18	SEG 17	SEG 16	SEG 23	SEG 22	SEG 21	SEG 20	SEG 19	SEG 18	SEG 17	SEG 16
P3	SEG 31	SEG 30	SEG 29	SEG 28	SEG 27	SEG 26	SEG 25	SEG 24	SEG 31	SEG 30	SEG 29	SEG 28	SEG 27	SEG 26	SEG 25	SEG 24
P4	SEG 39	SEG 38	—	—	—	—	—	—	SEG 39	SEG 38	SEG 37	SEG 36	SEG 35	SEG 34	SEG 33	SEG 32
P5	—	VL3 (2)	VL2 (2)	VL1 (2)	COM 0	COM 1	COM 2	COM 3	—	VL3 (2)	VL2 (2)	VL1 (2)	COM 0	COM 1	COM 2	COM 3

Notes:
1. The symbol "—" indicates there is no LCD display function. Set the corresponding bits to 0 by setting registers LSE1, LSE4 and LSE5 for these pins.
2. When using the LCD drive control circuit, set the corresponding bit in the LSE5 register to 1.

2. Central Processing Unit (CPU)

Figure 2.1 shows the CPU Registers. The CPU contains 13 registers. R0, R1, R2, R3, A0, A1, and FB configure a register bank. There are two sets of register banks.



Note:
1. These registers configure a register bank.
There are two sets of register banks.

Figure 2.1 CPU Registers

2.1 Data Registers (R0, R1, R2, and R3)

R0 is a 16-bit register for transfer, arithmetic, and logic operations. The same applies to R1 to R3. R0 can be split into high-order bits (R0H) and low-order bits (R0L) to be used separately as 8-bit data registers. R1H and R1L are analogous to R0H and R0L. R2 can be combined with R0 and used as a 32-bit data register (R2R0). R3R1 is analogous to R2R0.

2.2 Address Registers (A0 and A1)

A0 is a 16-bit register for address register indirect addressing and address register relative addressing. It is also used for transfer, arithmetic, and logic operations. A1 is analogous to A0. A1 can be combined with A0 and as a 32-bit address register (A1A0).

2.3 Frame Base Register (FB)

FB is a 16-bit register for FB relative addressing.

2.4 Interrupt Table Register (INTB)

INTB is a 20-bit register that indicates the starting address of an interrupt vector table.

2.5 Program Counter (PC)

PC is 20 bits wide and indicates the address of the next instruction to be executed.

2.6 User Stack Pointer (USP) and Interrupt Stack Pointer (ISP)

The stack pointers (SP), USP and ISP, are each 16 bits wide. The U flag of FLG is used to switch between USP and ISP.

2.7 Static Base Register (SB)

SB is a 16-bit register for SB relative addressing.

2.8 Flag Register (FLG)

FLG is an 11-bit register indicating the CPU state.

2.8.1 Carry Flag (C)

The C flag retains carry, borrow, or shift-out bits that have been generated by the arithmetic and logic unit.

2.8.2 Debug Flag (D)

The D flag is for debugging only. Set it to 0.

2.8.3 Zero Flag (Z)

The Z flag is set to 1 when an arithmetic operation results in 0; otherwise to 0.

2.8.4 Sign Flag (S)

The S flag is set to 1 when an arithmetic operation results in a negative value; otherwise to 0.

2.8.5 Register Bank Select Flag (B)

Register bank 0 is selected when the B flag is 0. Register bank 1 is selected when this flag is set to 1.

2.8.6 Overflow Flag (O)

The O flag is set to 1 when an operation results in an overflow; otherwise to 0.

Table 4.9 SFR Information for R8C/LA5A Group (9) (1)

Address	Register	Symbol	After Reset
0200h	LCD Control Register	LCR0	00h
0201h			
0202h	LCD Option Clock Control Register	LCR2	00h
0203h	LCD Clock Control Register	LCR3	00h
0204h	LCD Display Control Register	LCR4	00h
0205h			
0206h	LCD Port Select Register 0	LSE0	00h
0207h	LCD Port Select Register 1	LSE1	00h
0208h	LCD Port Select Register 2	LSE2	00h
0209h			
020Ah			
020Bh	LCD Port Select Register 5	LSE5	00h
020Ch			
020Dh			
020Eh			
020Fh			
0210h	LCD Display Data Register	LRA0L	XXh
0211h		LRA1L	XXh
0212h		LRA2L	XXh
0213h		LRA3L	XXh
0214h		LRA4L	XXh
0215h		LRA5L	XXh
0216h		LRA6L	XXh
0217h		LRA7L	XXh
0218h		LRA8L	XXh
0219h		LRA9L	XXh
021Ah		LRA10L	XXh
021Bh		LRA11L	XXh
021Ch		LRA12L	XXh
021Dh		LRA13L	XXh
021Eh		LRA14L	XXh
021Fh		LRA15L	XXh
0220h		LRA16L	XXh
0221h		LRA17L	XXh
0222h		LRA18L	XXh
0223h		LRA19L	XXh
0224h		LRA20L	XXh
0225h		LRA21L	XXh
0226h		LRA22L	XXh
0227h		LRA23L	XXh
0228h		LRA24L	XXh
0229h		LRA25L	XXh
022Ah		LRA26L	XXh
022Bh			
022Ch			
022Dh			
022Eh			
022Fh			
0230h			
0231h			
0232h			
0233h			
0234h			
0235h			
0236h			
0237h			
:			
2FFFh			

X: Undefined

Note:

1. Blank spaces are reserved. No access is allowed.

Table 4.12 SFR Information for R8C/LA8A Group (3) (1)

Address	Register	Symbol	After Reset
0080h	Timer RJ0 Control Register	TRJ0CR	00h
0081h	Timer RJ0 I/O Control Register	TRJ0IOC	00h
0082h	Timer RJ0 Mode Register	TRJ0MR	00h
0083h	Timer RJ0 Event Pin Select Register	TRJ0ISR	00h
0084h	Timer RJ0 Register	TRJ0	FFh
0085h			FFh
0086h			
0087h			
0088h	Timer RJ1 Control Register	TRJ1CR	00h
0089h	Timer RJ1 I/O Control Register	TRJ1IOC	00h
008Ah	Timer RJ1 Mode Register	TRJ1MR	00h
008Bh	Timer RJ1 Event Pin Select Register	TRJ1ISR	00h
008Ch	Timer RJ1 Register	TRJ1	FFh
008Dh			FFh
008Eh			
008Fh			
0090h	Timer RJ2 Control Register	TRJ2CR	00h
0091h	Timer RJ2 I/O Control Register	TRJ2IOC	00h
0092h	Timer RJ2 Mode Register	TRJ2MR	00h
0093h	Timer RJ2 Event Pin Select Register	TRJ2ISR	00h
0094h	Timer RJ2 Register	TRJ2	FFh
0095h			FFh
0096h			
0097h			
0098h	Timer RB1 Control Register	TRB1CR	00h
0099h	Timer RB1 One-Shot Control Register	TRB1OCR	00h
009Ah	Timer RB1 I/O Control Register	TRB1IOC	00h
009Bh	Timer RB1 Mode Register	TRB1MR	00h
009Ch	Timer RB1 Prescaler Register	TRB1PRE	FFh
009Dh	Timer RB1 Secondary Register	TRB1SC	FFh
009Eh	Timer RB1 Primary Register	TRB1PR	FFh
009Fh			
00A0h	UART0 Transmit/Receive Mode Register	U0MR	00h
00A1h	UART0 Bit Rate Register	U0BRG	XXh
00A2h	UART0 Transmit Buffer Register	U0TB	XXh
00A3h			XXh
00A4h	UART0 Transmit/Receive Control Register 0	U0C0	00001000b
00A5h	UART0 Transmit/Receive Control Register 1	U0C1	00000010b
00A6h	UART0 Receive Buffer Register	U0RB	XXh
00A7h			XXh
00A8h	UART2 Transmit/Receive Mode Register	U2MR	00h
00A9h	UART2 Bit Rate Register	U2BRG	XXh
00AAh	UART2 Transmit Buffer Register	U2TB	XXh
00ABh			XXh
00ACh	UART2 Transmit/Receive Control Register 0	U2C0	00001000b
00ADh	UART2 Transmit/Receive Control Register 1	U2C1	00000010b
00AEh	UART2 Receive Buffer Register	U2RB	XXh
00AFh			XXh
00B0h	UART2 Digital Filter Function Select Register	URXDF	00h
00B1h			
00B2h			
00B3h			
00B4h			
00B5h			
00B6h			
00B7h			
00B8h			
00B9h			
00BAh			
00BBh	UART2 Special Mode Register 5	U2SMR5	00h
00BCh	UART2 Special Mode Register 4	U2SMR4	00h
00BDh	UART2 Special Mode Register 3	U2SMR3	000X0X0Xb
00BEh	UART2 Special Mode Register 2	U2SMR2	X0000000b
00BFh	UART2 Special Mode Register	U2SMR	X0000000b

X: Undefined

Note:

1. Blank spaces are reserved. No access is allowed.

Table 4.14 SFR Information for R8C/LA8A Group (5) (1)

Address	Register	Symbol	After Reset
0100h			
0101h			
0102h			
0103h			
0104h			
0105h			
0106h			
0107h			
0108h	Timer RB0 Control Register	TRB0CR	00h
0109h	Timer RB0 One-Shot Control Register	TRB0OCR	00h
010Ah	Timer RB0 I/O Control Register	TRB0IOC	00h
010Bh	Timer RB0 Mode Register	TRB0MR	00h
010Ch	Timer RB0 Prescaler Register	TRB0PRE	FFh
010Dh	Timer RB0 Secondary Register	TRB0SC	FFh
010Eh	Timer RB0 Primary Register	TRB0PR	FFh
010Fh			
0110h	Timer RH Second Data Register / Counter Data Register	TRHSEC	XXh 00h (2)
0111h	Timer RH Minute Data Register / Compare Data Register	TRHMIN	XXh 00h (2)
0112h	Timer RH Hour Data Register	TRHHR	00XXXXXXb 00h (2)
0113h	Timer RH Day-of-the-Week Data Register	TRHWK	00000XXXb 00h (2)
0114h	Timer RH Date Data Register	TRHDY	00XXXXXXb 00000001b (2)
0115h	Timer RH Month Data Register	TRHMON	000XXXXXb 00000001b (2)
0116h	Timer RH Year Data Register	TRHYR	XXh 00h (2)
0117h	Timer RH Control Register	TRHCR	XXX00X0Xb 000XX1X0b (2)
0118h	Timer RH Count Source Select Register	TRHCSR	X0001000b 0XXXXXXXb (2)
0119h	Timer RH Clock Error Correction Register	TRHADJ	XXh 00h (2)
011Ah	Timer RH Interrupt Flag Register	TRHIFR	00000XXXb 000XX000b (2)
011Bh	Timer RH Interrupt Enable Register	TRHIER	XXh 00h (2)
011Ch	Timer RH Alarm Minute Register	TRHAMN	XXh 00h (2)
011Dh	Timer RH Alarm Hour Register	TRHAHR	XXh 00h (2)
011Eh	Timer RH Alarm Day-of-the-Week Register	TRHAWK	X0000XXXb 00h (2)
011Fh	Timer RH Protect Register	TRHPRC	00h X0000000b (2)
0120h	Timer RC Mode Register	TRCMR	01001000b
0121h	Timer RC Control Register 1	TRCCR1	00h
0122h	Timer RC Interrupt Enable Register	TRCIER	01110000b
0123h	Timer RC Status Register	TRCSR	01110000b
0124h	Timer RC I/O Control Register 0	TRCIOR0	10001000b
0125h	Timer RC I/O Control Register 1	TRCIOR1	10001000b
0126h	Timer RC Counter	TRC	00h
0127h			00h
0128h	Timer RC General Register A	TRCGRA	FFh
0129h			FFh
012Ah	Timer RC General Register B	TRCGRB	FFh
012Bh			FFh
012Ch	Timer RC General Register C	TRCGRC	FFh
012Dh			FFh
012Eh	Timer RC General Register D	TRCGRD	FFh
012Fh			FFh
0130h	Timer RC Control Register 2	TRCCR2	00011000b
0131h	Timer RC Digital Filter Function Select Register	TRCDF	00h
0132h	Timer RC Output Master Enable Register	TRCOER	01111111b
0133h	Timer RC Trigger Control Register	TRCADCR	00h
0134h			
0135h			
0136h			
0137h			
0138h			
0139h			
013Ah			
013Bh			
013Ch			
013Dh			
013Eh			
013Fh			

X: Undefined

Notes:

1. Blank spaces are reserved. No access is allowed.
2. This is the reset value after reset by RTCRST bit in TRHCR register.

Table 4.19 ID Code Areas and Option Function Select Area

Address	Area Name	Symbol	After Reset
:			
FFDBh	Option Function Select Register 2	OFS2	(Note 1)
:			
FFDFh	ID1		(Note 2)
:			
FFE3h	ID2		(Note 2)
:			
FFEBh	ID3		(Note 2)
:			
FFEFh	ID4		(Note 2)
:			
FFF3h	ID5		(Note 2)
:			
FFF7h	ID6		(Note 2)
:			
FFFBh	ID7		(Note 2)
:			
FFFFh	Option Function Select Register	OFS	(Note 1)

Notes:
1. The option function select area is allocated in the flash memory, not in the SFRs. Set appropriate values as ROM data by a program.
   Do not write additions to the option function select area. If the block including the option function select area is erased, the option function select area is set to FFh.
   When blank products are shipped, the option function select area is set to FFh. It is set to the written value after written by the user.
   When factory-programming products are shipped, the value of the option function select area is the value programmed by the user.
2. The ID code areas are allocated in the flash memory, not in the SFRs. Set appropriate values as ROM data by a program.
   Do not write additions to the ID code areas. If the block including the ID code areas is erased, the ID code areas are set to FFh.
   When blank products are shipped, the ID code areas are set to FFh. They are set to the written value after written by the user.
   When factory-programming products are shipped, the value of the ID code areas is the value programmed by the user.

Table 5.8 Flash Memory (Data flash Block A and Block B) Characteristics (V_{CC} = 1.8 to 5.5 V and T_{opr} = −20 to 85 °C (N version)/ −40 to 85 °C (D version), unless otherwise specified.)

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
–	Program/erase endurance (1)		10,000 (2)	–	–	times
–	Byte program time (program/erase endurance ≤ 10,000 times)		–	150	–	µs
–	Block erase time (program/erase endurance ≤ 10,000 times)		–	0.05	1	s
$t_{d(SR-SUS)}$	Time delay from suspend request until suspend		–	–	0.25 + CPU clock × 3 cycles	ms
–	Time from suspend until erase restart		–	–	30 + CPU clock × 1 cycle	µs
$t_{d(CMDRST-READY)}$	Time from when command is forcibly terminated until reading is enabled		–	–	30 + CPU clock × 1 cycle	µs
–	Program, erase voltage		1.8	–	5.5	V
–	Read voltage		1.8	–	5.5	V
–	Program, erase temperature		−20 (6)	–	85	°C
–	Data hold time (7)	Ambient temperature = 85 °C	10	–	–	year

Notes:
1. Definition of programming/erasure endurance
   The programming and erasure endurance is defined on a per-block basis.
   If the programming and erasure endurance is n (n = 10,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.
   However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
2. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
3. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. In addition, averaging the erasure endurance between blocks A and B can further reduce the actual erasure endurance. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.
4. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
5. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
6. −40 °C for D version.
7. The data hold time includes time that the power supply is off or the clock is not supplied.

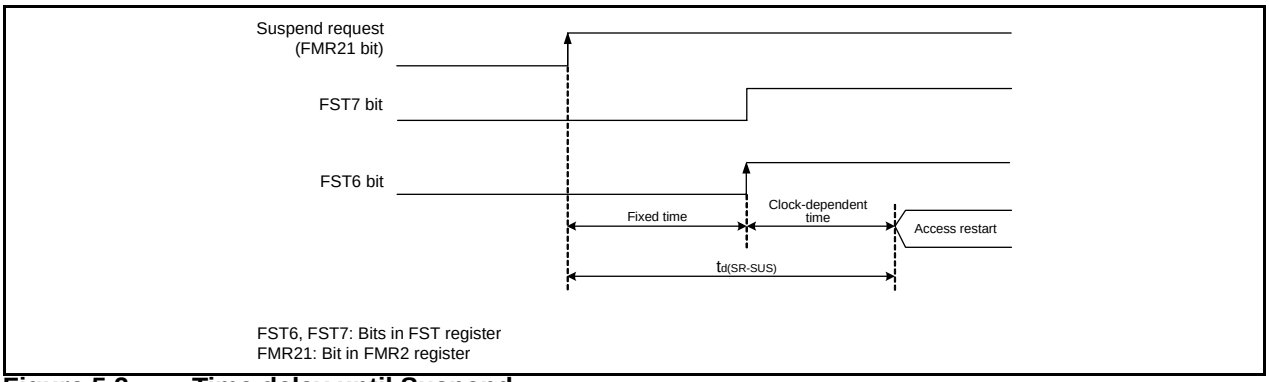


Figure 5.2 Time delay until Suspend

Table 5.13 High-speed On-Chip Oscillator Circuit Characteristics (VCC = 1.8 to 5.5 V and Topr = –20 to 85 °C (N version)/ –40 to 85 °C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
–	High-speed on-chip oscillator frequency after reset	VCC = 1.8 V to 5.5 V – 20 °C ≤ Topr ≤ 85 °C	19.2	20	20.8	MHz
		VCC = 1.8 V to 5.5 V – 40 °C ≤ Topr ≤ 85 °C	19.0	20	21.0	MHz
	High-speed on-chip oscillator frequency when the FRA4 register correction value is written into the FRA1 register and the FRA5 register correction value into the FRA3 register (1)	VCC = 1.8 V to 5.5 V – 20 °C ≤ Topr ≤ 85 °C	17.694	18.432	19.169	MHz
		VCC = 1.8 V to 5.5 V – 40 °C ≤ Topr ≤ 85 °C	17.510	18.432	19.353	MHz
–	Oscillation stability time		–	5	30	µs
–	Self power consumption at oscillation	VCC = 5.0 V, Topr = 25 °C	–	530	–	µA

Note:
1. This enables the setting errors of bit rates such as 9600 bps and 38400 bps to be 0% when the serial interface is used in UART mode.

Table 5.14 Low-speed On-Chip Oscillator Circuit Characteristics (VCC = 1.8 to 5.5 V and Topr = –20 to 85 °C (N version)/ –40 to 85 °C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
fOCO-S	Low-speed on-chip oscillator frequency		60	125	250	kHz
–	Oscillation stability time		–	–	35	µs
–	Self power consumption at oscillation	VCC = 5.0 V, Topr = 25°C	–	2	–	µA
fOCO-WDT	Low-speed on-chip oscillator frequency for the watchdog timer		60	125	250	kHz
–	Oscillation stability time		–	–	35	µs
–	Self power consumption at oscillation	VCC = 5.0 V, Topr = 25°C	–	2	–	µA

Table 5.15 Power Supply Circuit Characteristics (VCC = 1.8 to 5.5 V, Vss = 0 V, and Topr = 25 °C, unless otherwise specified.)

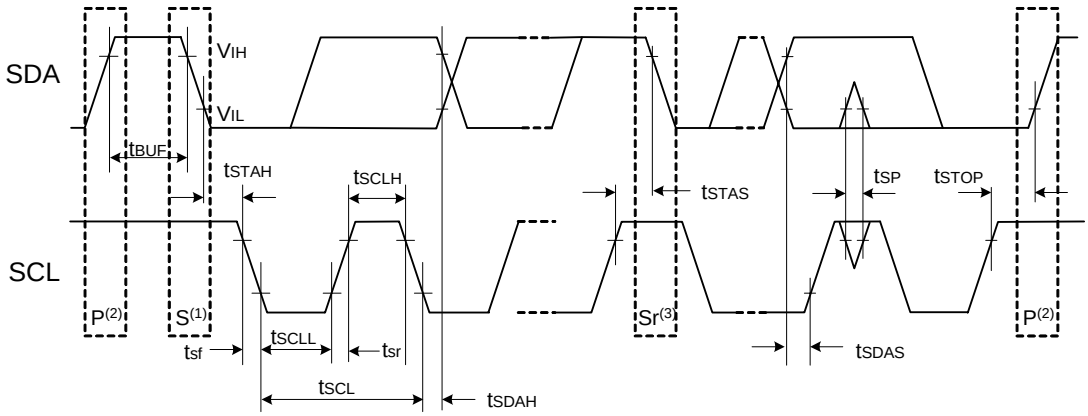
Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
td(P-R)	Time for internal power supply stabilization during power-on (1)		–	–	2000	µs

Note:
1. Waiting time until the internal power supply generation circuit stabilizes during power-on.

Table 5.25 Timing Requirements of I²C bus Interface (1)
(Vcc = 1.8 to 5.5 V, Vss = 0 V, and Topr = –20 to 85 °C (N version)/ –40 to 85 °C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
tSCL	SCL input cycle time		12tCYC + 600 (1)	–	–	ns
tSCLH	SCL input “H” width		3tCYC + 300 (1)	–	–	ns
tSCLL	SCL input “L” width		5tCYC + 500 (1)	–	–	ns
tsf	SCL, SDA input fall time		–	–	300	ns
tSP	SCL, SDA input spike pulse rejection time		–	–	1tCYC (1)	ns
tBUF	SDA input bus-free time		5tCYC (1)	–	–	ns
tSTAH	Start condition input hold time		3tCYC (1)	–	–	ns
tSTAS	Retransmit start condition input setup time		3tCYC (1)	–	–	ns
tSTOP	Stop condition input setup time		3tCYC (1)	–	–	ns
tSDAS	Data input setup time		1tCYC + 40 (1)	–	–	ns
tSDAH	Data input hold time		10	–	–	ns

Note:
1. 1tCYC = 1/f1(s)



Notes:
1. Start condition
2. Stop condition
3. Retransmit start condition

Figure 5.7 I/O Timing of I²C bus Interface

Table 5.26 Timing Requirements of External Clock Input (XIN, XCIN)
(Vss = 0 V and Topr = –20 to 85 °C (N version)/ –40 to 85 °C (D version), unless otherwise specified.)

Symbol	Parameter	Standard						Unit
		Vcc = 2.2V, Topr = 25°C		Vcc = 3V, Topr = 25°C		Vcc = 5V, Topr = 25°C		
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{c(XIN)}$	XIN input cycle time	200	–	50	–	50	–	ns
$t_{WH(XIN)}$	XIN input “H” width	90	–	24	–	24	–	ns
$t_{WL(XIN)}$	XIN input “L” width	90	–	24	–	24	–	ns
$t_{c(XCIN)}$	XCIN input cycle time	20	–	20	–	20	–	µs
$t_{WH(XCIN)}$	XCIN input “H” width	10	–	10	–	10	–	µs
$t_{WL(XCIN)}$	XCIN input “L” width	10	–	10	–	10	–	µs

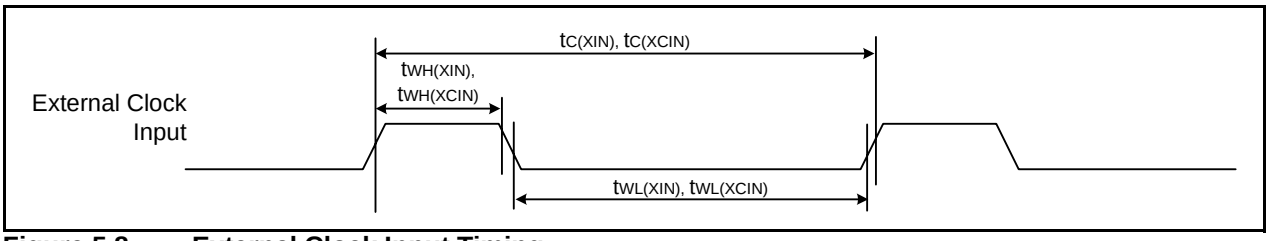


Figure 5.8 External Clock Input Timing

Table 5.27 Timing Requirements of TRJiIO (i = 0 or 1)
(Vss = 0 V and Topr = –20 to 85 °C (N version)/ –40 to 85 °C (D version), unless otherwise specified.)

Symbol	Parameter	Standard						Unit
		Vcc = 2.2V, Topr = 25°C		Vcc = 3V, Topr = 25°C		Vcc = 5V, Topr = 25°C		
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{c(TRJIO)}$	TRJiIO input cycle time	500	–	300	–	100	–	ns
$t_{WH(TRJIO)}$	TRJiIO input “H” width	200	–	120	–	40	–	ns
$t_{WL(TRJIO)}$	TRJiIO input “L” width	200	–	120	–	40	–	ns

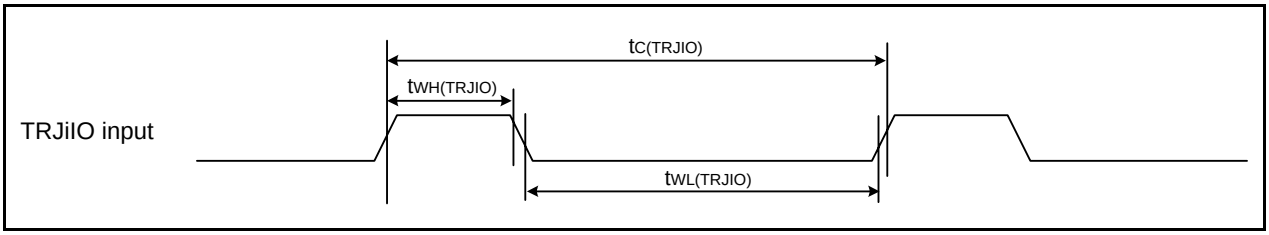


Figure 5.9 Input Timing of TRJiIO

5.2.3 Peripheral Function Characteristics

Table 5.32 A/D Converter Characteristics
(Vcc/AVcc = Vref = 1.8 to 5.5 V, Vss = 0 V, and Topr = –20 to 85°C (N version)/ –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter		Conditions		Standard			Unit
					Min.	Typ.	Max.	
–	Resolution		Vref = AVcc		–	–	10	Bit
–	Absolute accuracy (2)	10-bit mode	Vref = AVcc = 5.0 V	AN0 to AN11 input	–	–	±3	LSB
			Vref = AVcc = 2.2 V	AN0 to AN11 input	–	–	±5	LSB
			Vref = AVcc = 1.8 V	AN0 to AN11 input	–	–	±5	LSB
		8-bit mode	Vref = AVcc = 5.0 V	AN0 to AN11 input	–	–	±2	LSB
			Vref = AVcc = 2.2 V	AN0 to AN11 input	–	–	±2	LSB
			Vref = AVcc = 1.8 V	AN0 to AN11 input	–	–	±2	LSB
ϕAD	A/D conversion clock		4.0 ≤ Vref = AVcc ≤ 5.5 V (1)		1	–	20	MHz
			3.2 ≤ Vref = AVcc ≤ 5.5 V (1)		1	–	16	MHz
			2.7 ≤ Vref = AVcc ≤ 5.5 V (1)		1	–	10	MHz
			1.8 ≤ Vref = AVcc ≤ 5.5 V (1)		1	–	8	MHz
–	Tolerance level impedance				–	3	–	kΩ
tCONV	Conversion time	10-bit mode	Vref = AVcc = 5.0 V, ϕAD = 20 MHz		2.2	–	–	µs
		8-bit mode	Vref = AVcc = 5.0 V, ϕAD = 20 MHz		2.2	–	–	ms
tSAMP	Sampling time		ϕAD = 20 MHz		0.8	–	–	µs
IVref	Vref current		Vcc = 5 V, XIN = f1 = ϕAD = 20 MHz		-	45	–	µA
Vref	Reference voltage				1.8	–	AVcc	V
VIA	Analog input voltage (3)				0	–	Vref	V
OCVREF	On-chip reference voltage		2 MHz ≤ ϕAD ≤ 4 MHz		1.53	1.70	1.87	V

Notes:
1. The A/D conversion result will be undefined in wait mode, stop mode, power-off mode, when the flash memory stops, and in low-current-consumption mode. Do not perform A/D conversion in these states or transition to these states during A/D conversion.
2. This applies when the peripheral functions are stopped.
3. When the analog input voltage is over the reference voltage, the A/D conversion result will be 3FFh in 10-bit mode and FFh in 8-bit mode.

Table 5.33 Temperature Sensor Characteristics
(VSS = 0 V and Topr = –20 to 85 °C (N version)/–40 to 85 °C (D version), unless otherwise specified.)

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
VTMP	Temperature sensor output voltage	1.8 V ≤ Vref = AVcc ≤ 5.5 V ϕAD = 1.0 MHz to 5.0 MHz Ambient temperature = 25 °C	550	600	650	mV
–	Temperature coefficient	1.8 V ≤ Vref = AVcc ≤ 5.5 V ϕAD = 1.0 MHz to 5.0 MHz Ambient temperature = 25 °C	–	–2.1	–	mV/°C
–	Start-up time	1.8 V ≤ Vref = AVcc ≤ 5.5 V ϕAD = 1.0 MHz to 5.0 MHz	–	–	200	µs
ITMP	Operating current	1.8 V ≤ Vref = AVcc ≤ 5.5 V ϕAD = 1.0 MHz to 5.0 MHz	–	100	–	µA

Table 5.34 Gain Amplifier Characteristics
(VSS = 0 V and Topr = –20 to 85 °C (N version)/–40 to 85 °C (D version), unless otherwise specified.)

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
VGAIN	Gain amplifier operating range		0.4	–	AVCC – 1.0	V
ϕAD	A/D conversion clock		1	–	5	MHz

Table 5.35 Comparator B Characteristics
(VCC = 1.8 to 5.5 V and Topr = –20 to 85°C (N version)/ –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
Vref	IVREF1, IVREF3 input reference voltage		0	–	VCC – 1.4	V
VI	IVCMP1, IVCMP3 input voltage		-0.3	–	VCC + 0.3	V
–	Offset		–	5	100	mV
td	Comparator output delay time (1)	VI = Vref ± 100 mV	–	–	1	µs
ICMP	Comparator operating current	VCC = 5.0 V	–	12	–	µA

Note:
1. When the digital filter is disabled.

Table 5.36 Flash Memory (Program ROM) Characteristics
(VCC = 1.8 to 5.5 V and Topr = 0 to 60°C, unless otherwise specified.)

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
–	Program/erase endurance (1)		10,000 (2)	–	–	times
–	Byte program time		–	80	–	µs
–	Block erase time	Internal ROM Capacity: 16 KB, 32 KB, 48 KB, 64 KB	–	0.12	–	s
		Internal ROM Capacity: 96 KB, 128 KB	–	0.2	–	s
td(SR-SUS)	Time delay from suspend request until suspend		–	–	0.25 + CPU clock × 3 cycles	ms
–	Time from suspend until erase restart		–	–	30 + CPU clock × 1 cycle	µs
td(CMDRST-READY)	Time from when command is forcibly terminated until reading is enabled		–	–	30 + CPU clock × 1 cycle	µs
–	Program, erase voltage		1.8	–	5.5	V
–	Read voltage		1.8	–	5.5	V
–	Program, erase temperature		0	–	60	°C
–	Data hold time (6)	Ambient temperature = 85°C	10	–	–	year

Notes:
1. Definition of programming/erasure endurance
   The programming and erasure endurance is defined on a per-block basis.
   If the programming and erasure endurance is n (n = 1,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.
   However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
2. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
3. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.
4. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
5. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
6. The data hold time includes time that the power supply is off or the clock is not supplied.

Table 5.40 Voltage Detection 2 Circuit Characteristics
(V_{CC} = 1.8 to 5.5 V and T_{opr} = –20 to 85°C (N version)/ –40 to 85°C (D version), unless otherwise specified.)

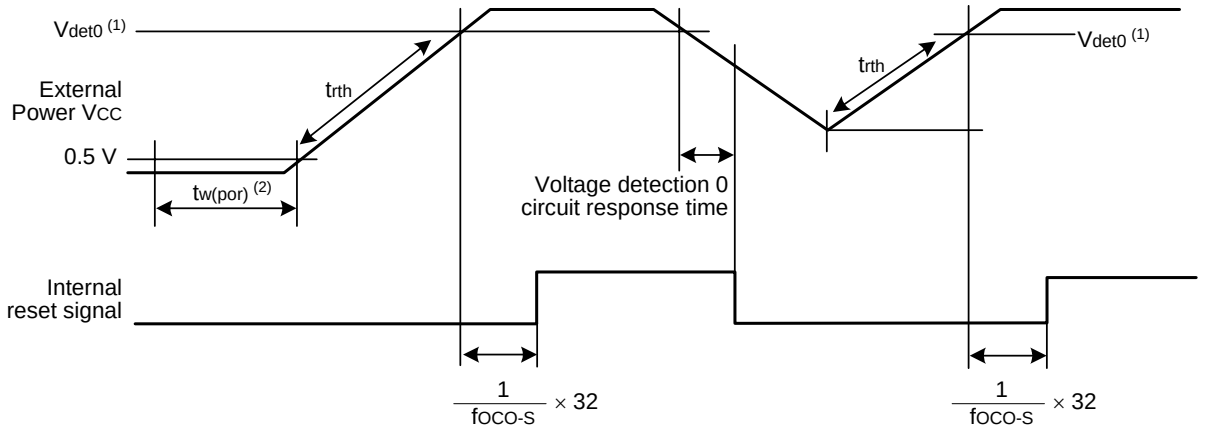
Symbol	Parameter	Condition		Standard			Unit
				Min.	Typ.	Max.	
V_{det2}	Voltage detection level Vdet2_0 (1)	At the falling of V_{CC}		3.70	4.0	4.30	V
–	Hysteresis width at the rising of Vcc in voltage detection 2 circuit			–	0.10	–	V
–	Voltage detection 2 circuit response time (2)	In operation	At the falling of Vcc from 5 V to (Vdet2_0 – 0.1) V	–	20	150	µs
		In stop mode	At the falling of Vcc from 5 V to (Vdet2_0 – 0.1) V	–	200	500	µs
–	Voltage detection circuit self power consumption	VCA27 = 1, V_{CC} = 5.0 V		–	1.7	–	µA
$t_{d(E-A)}$	Waiting time until voltage detection circuit operation starts (3)			–	–	100	µs

Notes:
1. The voltage detection level varies with detection targets. Select the level with the VCA24 bit in the VCA2 register.
2. Time until the voltage monitor 2 interrupt request is generated after the voltage passes V_{det2}.
3. Necessary time until the voltage detection circuit operates after setting to 1 again after setting the VCA27 bit in the VCA2 register to 0.

Table 5.41 Power-on Reset Circuit Characteristics (1)
(T_{opr} = –20 to 85°C (N version)/ –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
t_{rth}	External power V_{CC} rise gradient		0	–	50000	mV/ms

Note:
1. To use the power-on reset function, enable voltage monitor 0 reset by setting the LVDAS bit in the OFS register to 0.



Notes:
1. V_{det0} indicates the voltage detection level of the voltage detection 0 circuit. Refer to **6. Voltage Detection Circuit** in the User's Manual: Hardware for details.
2. $t_{w(por)}$ indicates the duration the external power V_{CC} must be held below the valid voltage (0.5 V) to enable a power-on reset. When turning on the power after it falls with voltage monitor 0 reset disabled, maintain $t_{w(por)}$ for 1 ms or more.

Figure 5.14 Power-on Reset Circuit Characteristics

Table 5.42 High-speed On-Chip Oscillator Circuit Characteristics (VCC = 1.8 to 5.5 V and Topr = –20 to 85°C (N version)/ –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
–	High-speed on-chip oscillator frequency after reset	VCC = 1.8 V to 5.5 V – 20°C ≤ Topr ≤ 85°C	19.2	20	20.8	MHz
		VCC = 1.8 V to 5.5 V – 40°C ≤ Topr ≤ 85°C	19.0	20	21.0	MHz
	High-speed on-chip oscillator frequency when the FRA4 register correction value is written into the FRA1 register and the FRA5 register correction value into the FRA3 register (1)	VCC = 1.8 V to 5.5 V – 20°C ≤ Topr ≤ 85°C	17.694	18.432	19.169	MHz
		VCC = 1.8 V to 5.5 V – 40°C ≤ Topr ≤ 85°C	17.510	18.432	19.353	MHz
–	Oscillation stability time		–	5	30	µs
–	Self power consumption at oscillation	VCC = 5.0 V, Topr = 25°C	–	530	–	µA

Note:
1. This enables the setting errors of bit rates such as 9600 bps and 38400 bps to be 0% when the serial interface is used in UART mode.

Table 5.43 Low-speed On-Chip Oscillator Circuit Characteristics (VCC = 1.8 to 5.5 V and Topr = –20 to 85°C (N version)/ –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
fOCO-S	Low-speed on-chip oscillator frequency		60	125	250	kHz
–	Oscillation stability time		–	–	35	µs
–	Self power consumption at oscillation	VCC = 5.0 V, Topr = 25°C	–	2	–	µA
fOCO-WDT	Low-speed on-chip oscillator frequency for the watchdog timer		60	125	250	kHz
–	Oscillation stability time		–	–	35	µs
–	Self power consumption at oscillation	VCC = 5.0 V, Topr = 25°C	–	2	–	µA

Table 5.44 Power Supply Circuit Characteristics (VCC = 1.8 to 5.5 V, VSS = 0 V, and Topr = 25°C, unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
td(P-R)	Time for internal power supply stabilization during power-on (1)		–	–	2000	µs

Note:
1. Waiting time until the internal power supply generation circuit stabilizes during power-on.

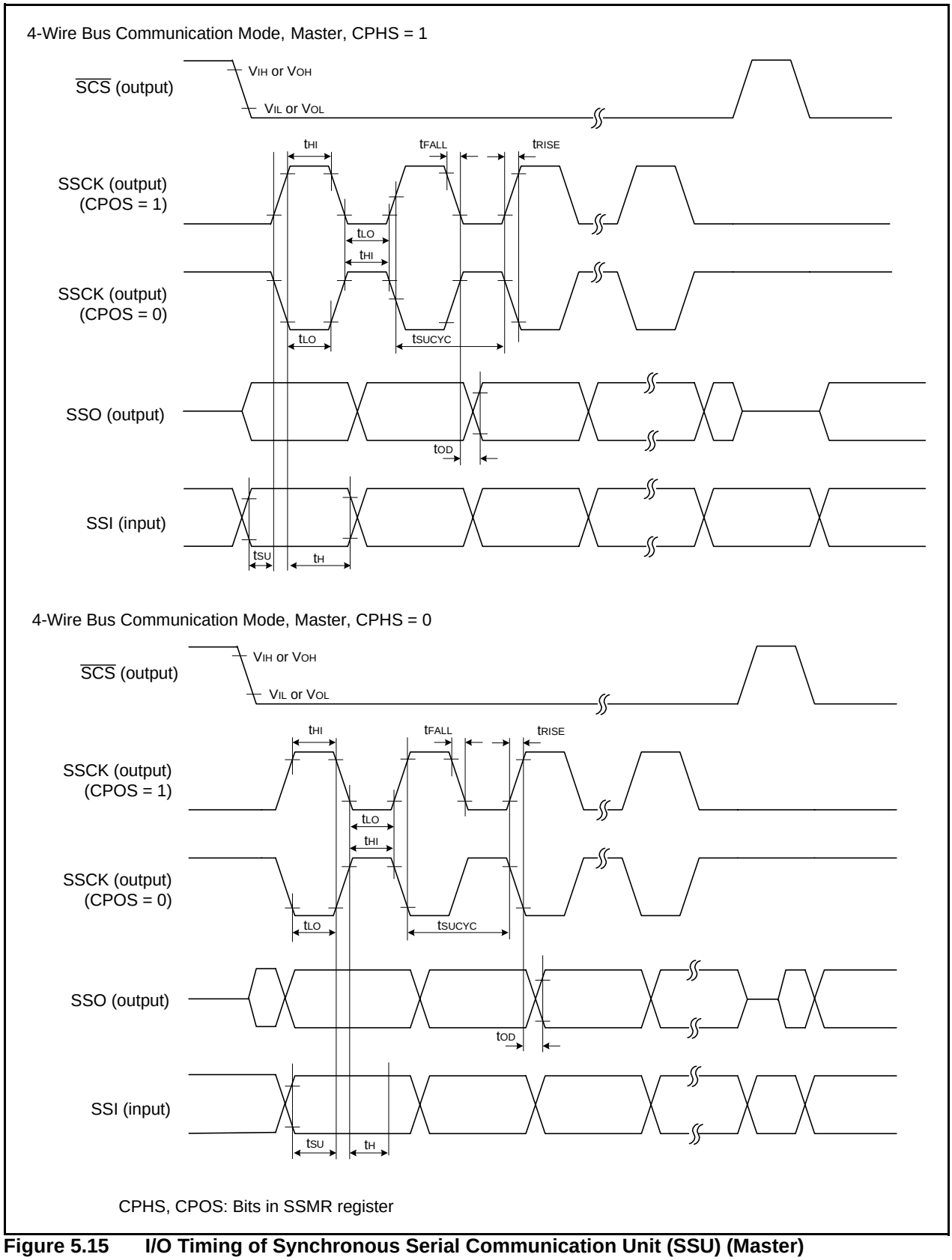


Figure 5.15 I/O Timing of Synchronous Serial Communication Unit (SSU) (Master)

Table 5.55 Timing Requirements of External Clock Input (XIN, XCIN)
(Vss = 0 V and Topr = –20 to 85°C (N version)/ –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Standard						Unit
		Vcc = 2.2V, Topr = 25°C		Vcc = 3V, Topr = 25°C		Vcc = 5V, Topr = 25°C		
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{c(XIN)}$	XIN input cycle time	200	–	50	–	50	–	ns
$t_{WH(XIN)}$	XIN input “H” width	90	–	24	–	24	–	ns
$t_{WL(XIN)}$	XIN input “L” width	90	–	24	–	24	–	ns
$t_{c(XCIN)}$	XCIN input cycle time	20	–	20	–	20	–	µs
$t_{WH(XCIN)}$	XCIN input “H” width	10	–	10	–	10	–	µs
$t_{WL(XCIN)}$	XCIN input “L” width	10	–	10	–	10	–	µs

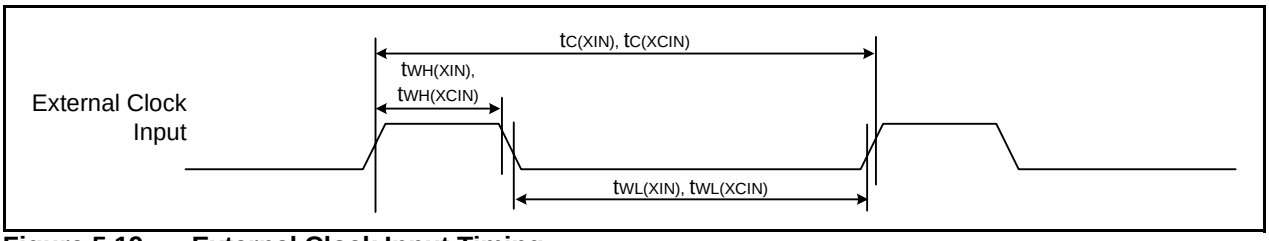


Figure 5.19 External Clock Input Timing

Table 5.56 Timing Requirements of TRJiIO (i = 0 to 2)
(Vss = 0 V and Topr = –20 to 85°C (N version)/ –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Standard						Unit
		Vcc = 2.2V, Topr = 25°C		Vcc = 3V, Topr = 25°C		Vcc = 5V, Topr = 25°C		
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{c(TRJIO)}$	TRJiIO input cycle time	500	–	300	–	100	–	ns
$t_{WH(TRJIO)}$	TRJiIO input “H” width	200	–	120	–	40	–	ns
$t_{WL(TRJIO)}$	TRJiIO input “L” width	200	–	120	–	40	–	ns

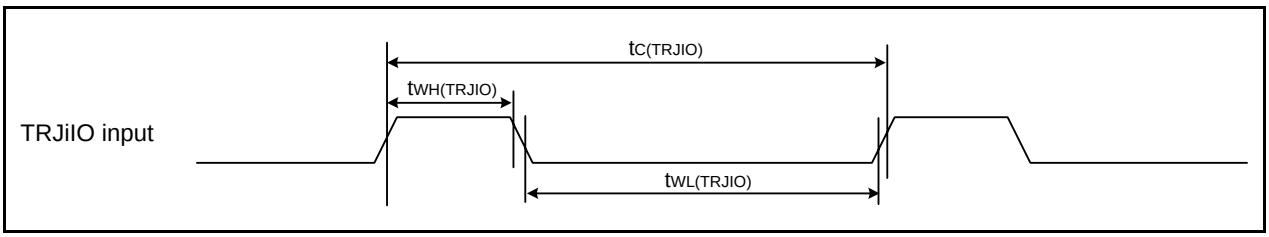
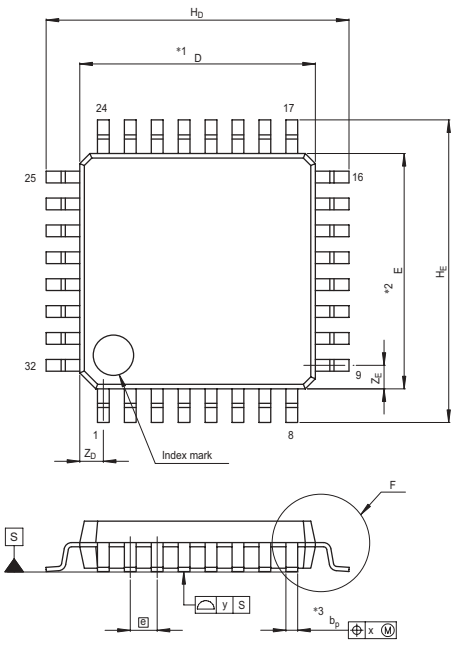


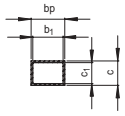
Figure 5.20 Input Timing of TRJiIO

Package Dimensions

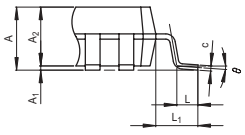
Diagrams showing the latest package dimensions and mounting information are available in the “Packages” section of the Renesas Electronics web site.

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LQFP32-7x7-0.80	PLQP0032GB-A	32P6U-A	0.2g





Terminal cross section

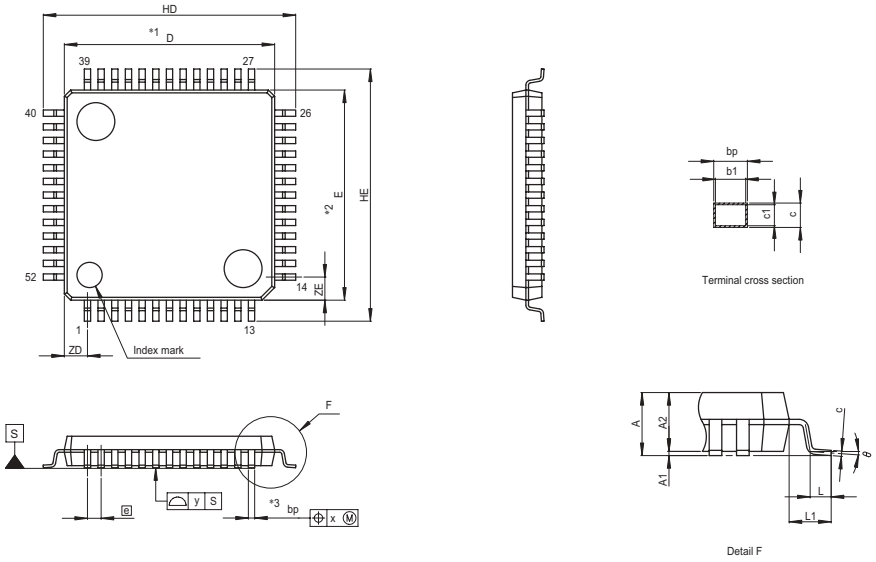


Detail F

NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	6.9	7.0	7.1
E	6.9	7.0	7.1
A_2	—	1.4	—
H_D	8.8	9.0	9.2
H_E	8.8	9.0	9.2
A	—	—	1.7
A_1	0	0.1	0.2
b_p	0.32	0.37	0.42
b_1	—	0.35	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.8	—
x	—	—	0.20
y	—	—	0.10
Z_D	—	0.7	—
Z_E	—	0.7	—
L	0.3	0.5	0.7
L_1	—	1.0	—

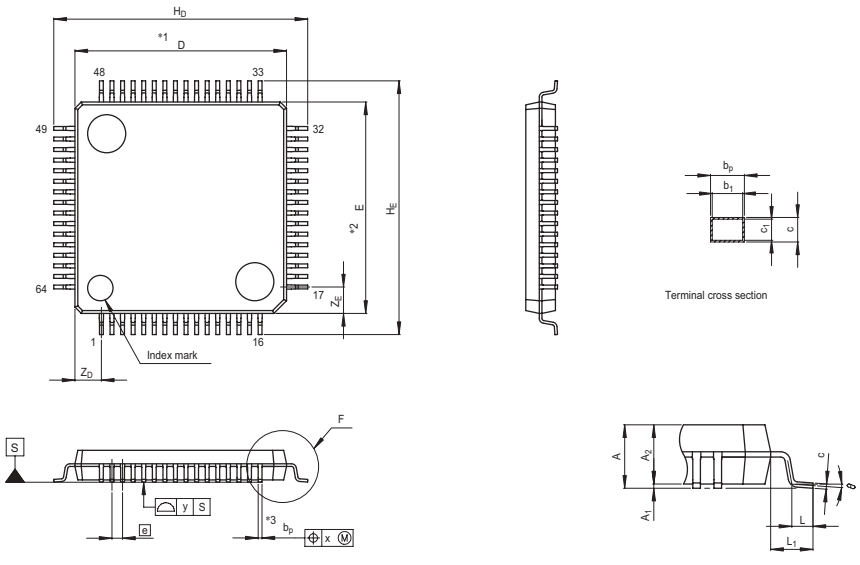
JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LQFP52-10x10-0.65	PLQP0052JA-A	52P6A-A	0.3g



NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	9.9	10.0	10.1
E	9.9	10.0	10.1
A_2	—	1.4	—
H_D	11.8	12.0	12.2
H_E	11.8	12.0	12.2
A	—	—	1.7
A_1	0.05	0.1	0.15
b_p	0.27	0.32	0.37
b_1	—	0.30	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.65	—
x	—	—	0.13
y	—	—	0.10
Z_D	—	1.1	—
Z_E	—	1.1	—
L	0.35	0.5	0.65
L_1	—	1.0	—

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LQFP64-10x10-0.50	PLQP0064KB-A	64P6Q-A / FP-64K / FP-64KV	0.3g



NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	9.9	10.0	10.1
E	9.9	10.0	10.1
A_2	—	1.4	—
H_D	11.8	12.0	12.2
H_E	11.8	12.0	12.2
A	—	—	1.7
A_1	0.05	0.1	0.15
b_p	0.15	0.20	0.25
b_1	—	0.18	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.5	—
x	—	—	0.08
y	—	—	0.08
Z_D	—	1.25	—
Z_E	—	1.25	—
L	0.35	0.5	0.65
L_1	—	1.0	—

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